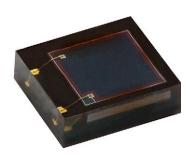


### Silicon PIN Photodiode



#### **DESCRIPTION**

VEMD2704 is a high speed and high sensitive PIN photodiode with enhanced sensitivity for visible light. It is optimized for heart rate monitoring and pulse oximetry applications.

#### **FEATURES**

- Package type: surface-mount
- · Package form: top view



- Radiant sensitive area (in mm<sup>2</sup>): 1.51
- · Clear epoxy for maximum sensitivity
- Suitable for visible and near infrared radiation
- Angle of half sensitivity:  $\varphi = \pm 67^{\circ}$
- Floor life: 168 h, MSL 3, according to J-STD-020







# RoHS

HALOGEN FREE GREEN

#### **APPLICATIONS**

- · Heart rate monitoring and pulse oximetry
- Wearables

PRODUCT SUMMARY				
COMPONENT	$I_{\rm ra}$ (μA) at E <sub>e</sub> = 0.1 mW/cm <sup>2</sup> , $\lambda$ = 530 nm, V <sub>R</sub> = 5.0 V	φ (°)	λ <sub>0.1</sub> (nm)	
VEMD2704	0.48	± 67	350 to 1100	

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VEMD2704	Tape and reel	MOQ: 4000	Top view		

#### Note

• MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T <sub>amb</sub> = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_{R}$	6	V
Ambient temperature range		T <sub>amb</sub>	-40 to +85	°C
Storage temperature range		T <sub>stg</sub>	-40 to +85	°C
Soldering temperature	According to reflow solder profile Fig. 7	$T_{sd}$	260	°C
ESD safety HBM	± 2000 V, 1.5 kΩ, 100 pF, 3 pulses	ESD <sub>HBM</sub>	≥2	kV

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<b>BASIC CHARACTERISTICS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I <sub>F</sub> = 50 mA	V <sub>F</sub>	1.0	1.2	1.3	V
Reverse dark current	V <sub>R</sub> = 10 V, E = 0	I <sub>ro</sub>	-	0.03	40	nA
Diode capacitance	$V_R = 0 V, f = 1 MHz, E = 0$	$C_D$	ı	17.6	-	pF
Reverse light current (1)	$E_e = 0.1 \text{ mW/cm}^2, \lambda = 530 \text{ nm}, V_R = 5 \text{ V}$	I <sub>ra</sub>	0.35	0.48	0.65	μA
	$E_e = 0.1 \text{ mW/cm}^2, \lambda = 660 \text{ nm}, V_R = 5 \text{ V}$	I <sub>ra</sub>	-	0.77	-	μA
	$E_e = 0.1 \text{ mW/cm}^2, \lambda = 850 \text{ nm}, V_R = 5 \text{ V}$	I <sub>ra</sub>	0.75	1.13	1.40	μΑ
	$E_e = 0.1 \text{ mW/cm}^2$ , $\lambda = 940 \text{ nm}$ , $V_R = 5 \text{ V}$	I <sub>ra</sub>	0.85	1.17	1.50	μA
Angle of half sensitivity		φ	-	± 67	-	0
Wavelength of peak sensitivity		$\lambda_{p}$	-	940	-	nm
Range of spectral bandwidth		λ <sub>0.1</sub>	-	350 to 1100	-	nm
Rise time	$V_R = 5 \text{ V}, \ R_L = 50 \ \Omega, \ \lambda = 530 \ \text{nm}$	t <sub>r</sub>	-	70	=	ns
Fall time	$V_R = 5 \text{ V}, \ R_L = 50 \ \Omega, \ \lambda = 530 \ \text{nm}$	t <sub>f</sub>	=	70	=	ns

#### Note

#### **BASIC CHARACTERISTICS** (T<sub>amb</sub> = 25 °C, unless otherwise specified)

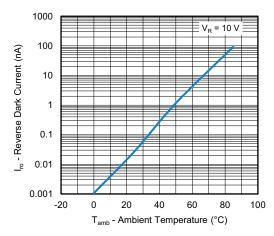


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

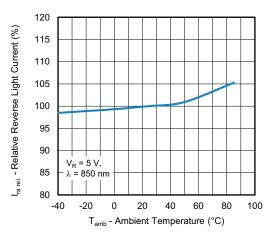


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

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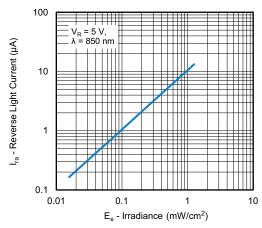


Fig. 3 - Reverse Light Current vs. Irradiance

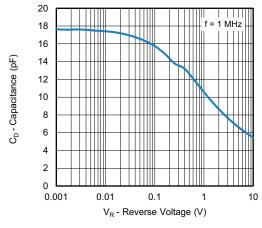


Fig. 4 - Diode Capacitance vs. Reverse Voltage

<sup>(1)</sup> The reverse light current for other irradiances can be estimated by linear extrapolation



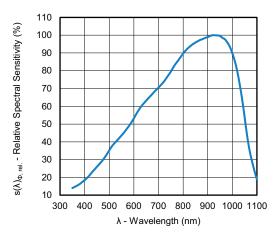


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

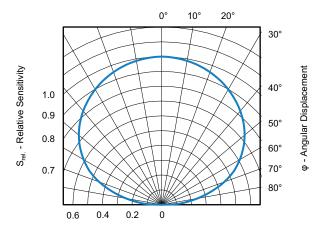
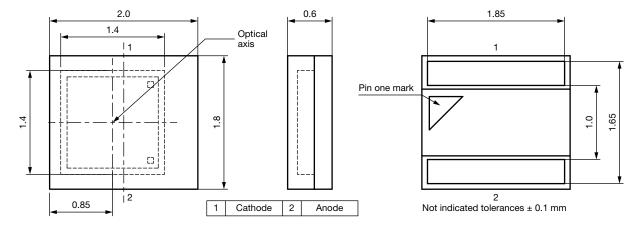
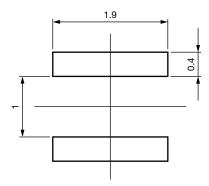


Fig. 6 - Relative Sensitivity vs. Angular Displacement

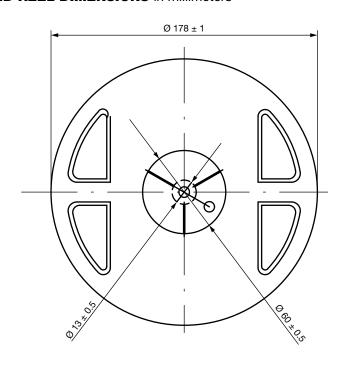
#### **PACKAGE DIMENSIONS** in millimeters

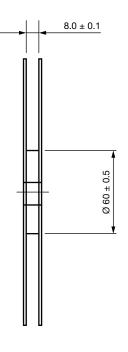


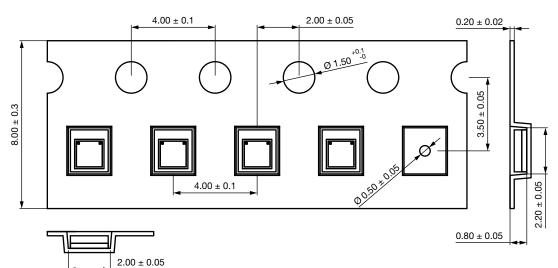
#### **RECOMMENDED FOOTPRINT** in millimeters



#### TAPE AND REEL DIMENSIONS in millimeters









#### **SOLDER PROFILE**

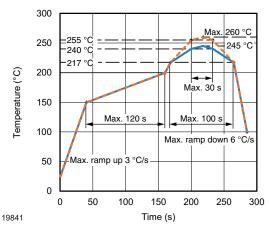


Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020D

#### **DRYPACK**

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

#### **FLOOR LIFE**

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 3

Floor life: 168 h

Conditions:  $T_{amb}$  < 30 °C, RH < 60 %

#### **DRYING**

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-033D or recommended conditions:

192 h at 40 °C (+ 5 °C), RH < 5 %

or

96 h at 60 °C (+ 5 °C), RH < 5 %



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